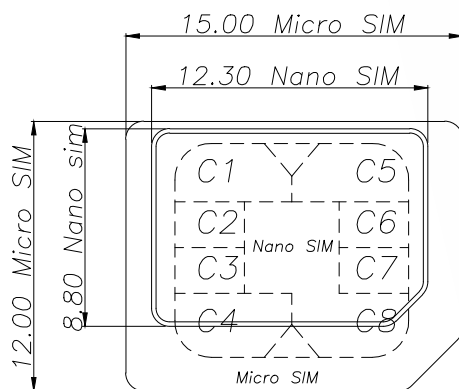
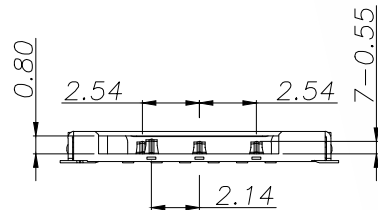
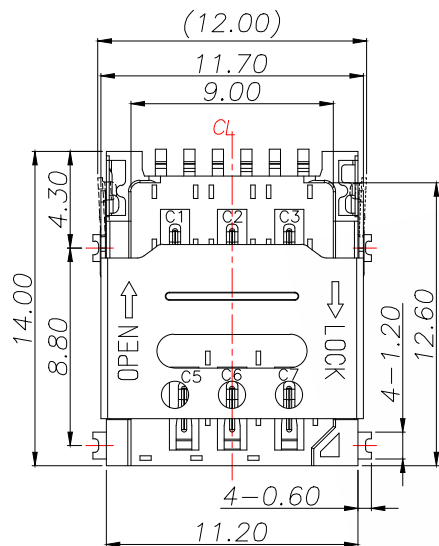
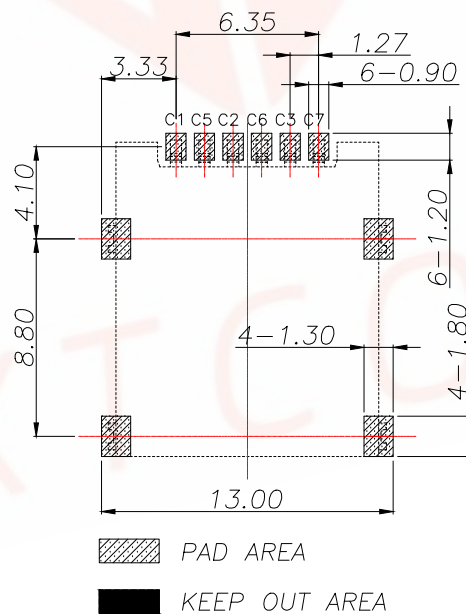
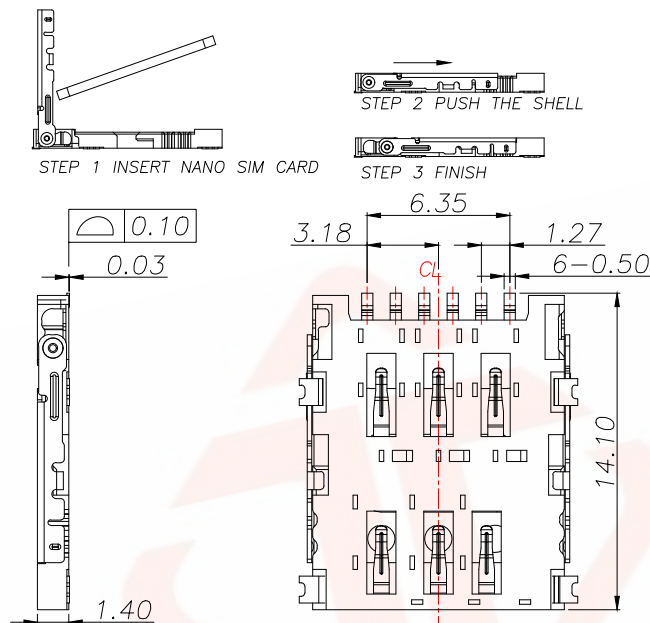


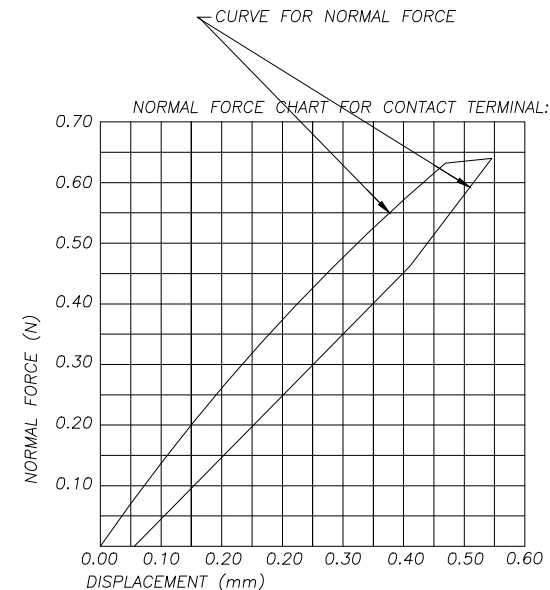


NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A



RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ± 0.05

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN



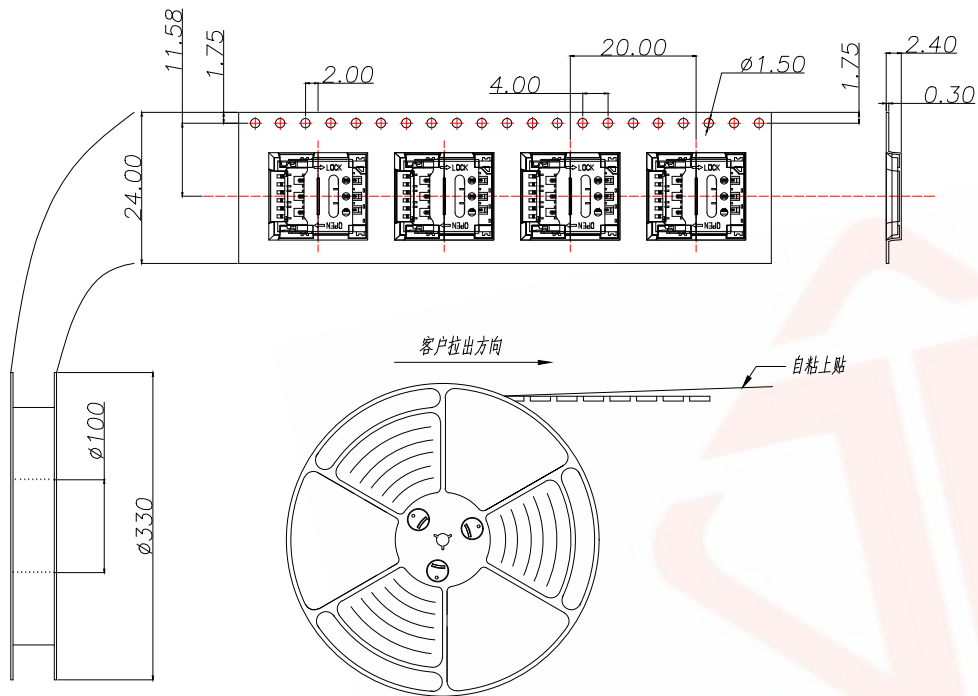
NOTES:

- MATERIAL:
 - Housing: High Temperature Thermoplastic UL94V-0; Color Black.
 - Terminal: Copper Alloy, $T=0.12\text{mm}$.
 - Shell: Stainless Steel, $T=0.20\text{mm}$.
- FINISH:
 - Terminal: Plated Gold on The Contact Area and Solder Tails.
 - Peg: Plated Gold on the Solder Tails.
- SPECIALITY:
 - Rated current: 0.5A
 - Rated voltage: 50V
 - Contact Resistance: 80mQMAX
 - Insulation Resistance: 100MΩMIN 100V DC
 - Dielectric withstanding voltage: 100V AC.
 - Solder ability: $245\pm 5^\circ\text{C}$, $5\pm 0.5\text{s}$.
 - Operating condition: Temperature: $-30^\circ\text{C}\sim +80^\circ\text{C}$ Humidity: 80% R.H MAX

③	TERMINAL	6	C5210-EH, $T=0.12$	Au 3u" PLATING
②	BASE INSULATOR	1	LCP+GF30%	BLACK
①	SHELL	1	SUS304-H, $T=0.15$	AU/Ni PLATING
NO.	PART NAME	Q'TY	DESCRIPTION	NOTE

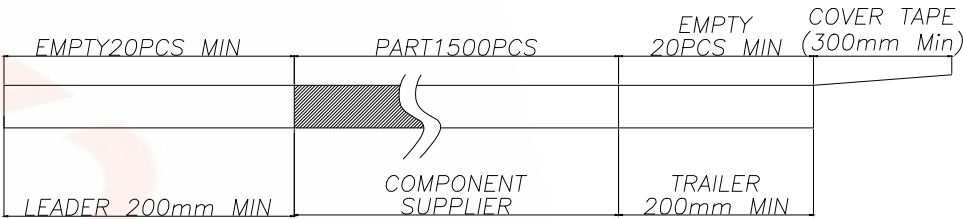
TOLERANCE		 深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd		
$X.: \pm 0.50$	$X': \pm 2'$	PART NO. CSIM-H135-XG6P	TITLE: 6PIN 1.4H HINGE NANO SIM CARD CONN.	
$X.X: \pm 0.20$	$X.X': \pm 1'$			
$X.XX: \pm 0.10$				
UNITS	mm	DESIGN: Ethan	MANUFACTURE DWG	
MATERILA	---	CHED: Olvia		
FINISH	---	APPD: Ava		
			 SCALE N:A	SHEET 1/1

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

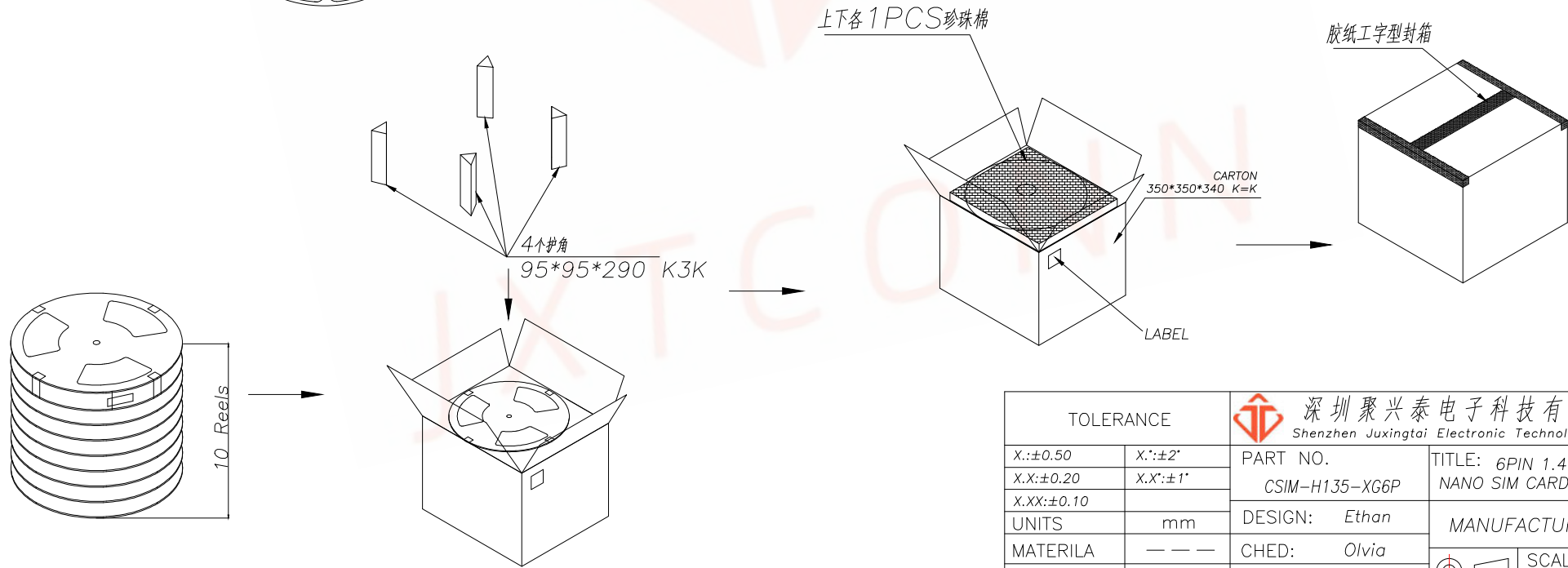


NOTES

1. NUMBER OF CONNECTORS:1500PCS/REEL
2. LEAD TAPE LENGTH



3. QUANTITY:15000PCS/CARTON



TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd			
X.:±0.50	X'.:±2"	PART NO. CSIM-H135-XG6P		TITLE: 6PIN 1.4H HINGE NANO SIM CARD CONN. 封装	
X.X:±0.20	X.X'.:±1"				
X.XX:±0.10					
UNITS	mm	DESIGN: Ethan		 MANUFACTURE DWG	
MATERILA	— — —	CHED: Olvia			
FINISH	— — —	APPD: Ava			
				SCALE	SHEET
				N:A	1/1